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(12) **United States Design Patent** (10) **Patent No.:** **US D941,788 S**  
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(54) **CIRCUIT BOARD**

(71) Applicants: **Norman R. Byrne**, Ada, MI (US);  
**Daniel P. Byrne**, Lowell, MI (US);  
**Aaron G. Lautenbach**, Rockford, MI  
(US); **Hansen Ma**, Grand Rapids, MI  
(US); **Peter J. Maher**, Grand Rapids,  
MI (US); **Shawn R. Gibson**, Fremont,  
MI (US)

(72) Inventors: **Norman R. Byrne**, Ada, MI (US);  
**Daniel P. Byrne**, Lowell, MI (US);  
**Aaron G. Lautenbach**, Rockford, MI  
(US); **Hansen Ma**, Grand Rapids, MI  
(US); **Peter J. Maher**, Grand Rapids,  
MI (US); **Shawn R. Gibson**, Fremont,  
MI (US)

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

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361/808, 736, 719, 720; 174/250, 253,  
174/255, 68.1; 363/144, 147  
CPC ..... H05K 3/30; H05K 3/301; H05K 3/284;  
H05K 3/303; H05K 1/18; H05K 1/181;  
H05K 1/182; H05K 1/183; H05K 1/185;  
H05K 1/00; H05K 7/1417; H05K 7/02;  
H05K 7/12; H05K 7/06; H01L 2924/14  
See application file for complete search history.

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(Continued)

*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Gardner, Linn, Burkhardt  
& Ondersma LLP

(57) **CLAIM**

The ornamental design for a circuit board, as shown and  
described.

**DESCRIPTION**

FIG. 1 is a top-front perspective view of a circuit board  
showing our new design;  
FIG. 2 is top-rear perspective view thereof;  
FIG. 3 is another top-front perspective view thereof;  
FIG. 4 is a bottom-front perspective view thereof;  
FIG. 5 is a bottom-rear perspective view thereof;  
FIG. 6 is a top plan view thereof;  
FIG. 7 is a bottom plan view thereof;  
FIG. 8 is a front elevation thereof;  
FIG. 9 is a rear elevation thereof;  
FIG. 10 is a side elevation view thereof;  
FIG. 11 is an opposite side elevation view thereof;  
FIG. 12 is another top-front perspective view of the circuit  
board of FIG. 1, with circuit structures shown in broken lines  
omitted to show the underlying structure;  
FIG. 13 is a bottom-rear perspective view thereof;  
FIG. 14 is another top-front perspective view thereof;  
FIG. 15 is a top-rear perspective view thereof;  
FIG. 16 is a bottom-front perspective view thereof;  
FIG. 17 is a top plan view thereof;  
FIG. 18 is a bottom plan view thereof;  
FIG. 19 is a front elevation thereof;  
FIG. 20 is a rear elevation thereof;  
FIG. 21 is a side elevation view thereof; and,  
FIG. 22 is an opposite side elevation view thereof.  
The broken lines in the drawings are for the purpose of  
illustrating portions of the circuit board that form no part of  
the claimed design.

**1 Claim, 15 Drawing Sheets**



(56)

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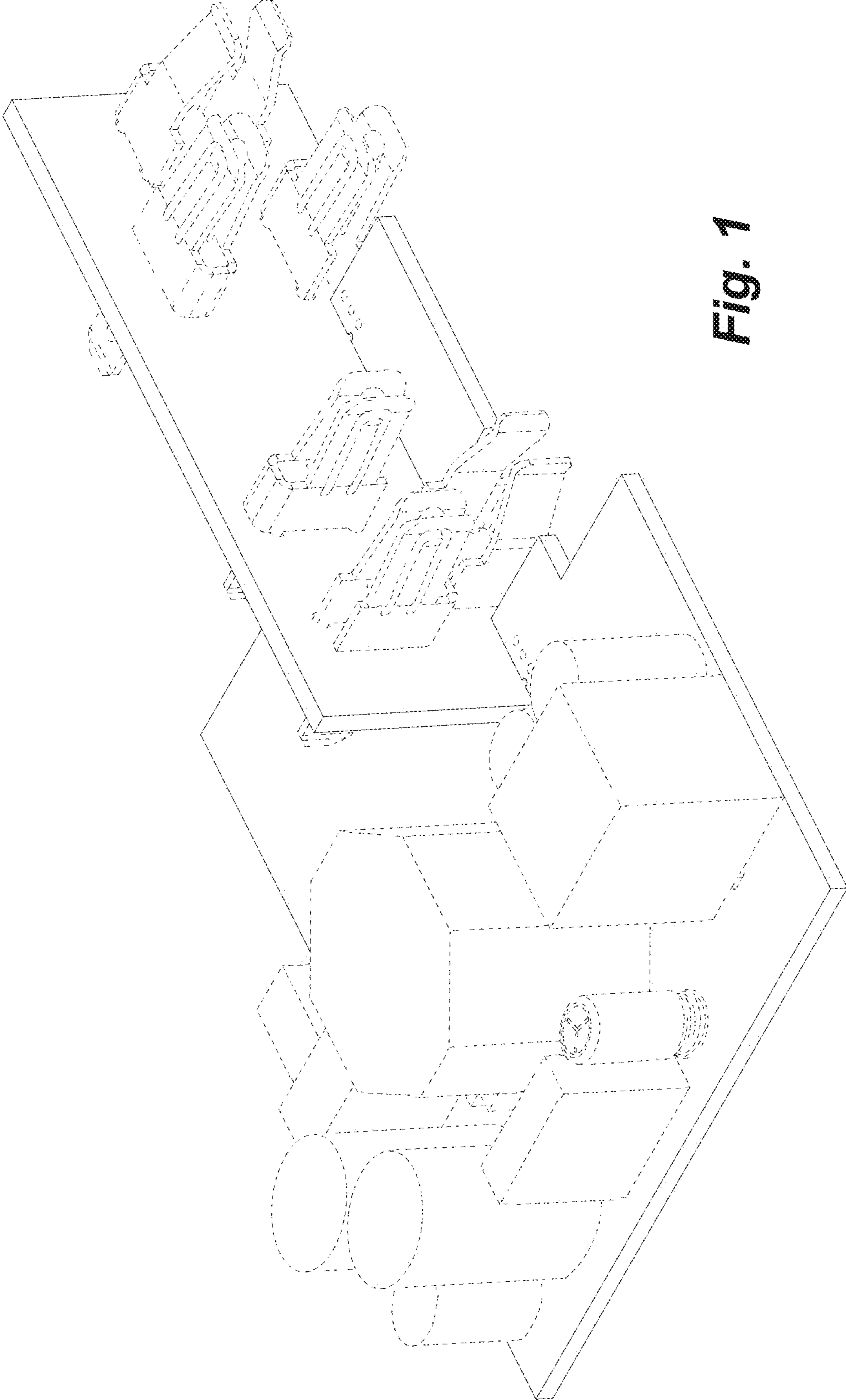


Fig. 1

Fig. 2

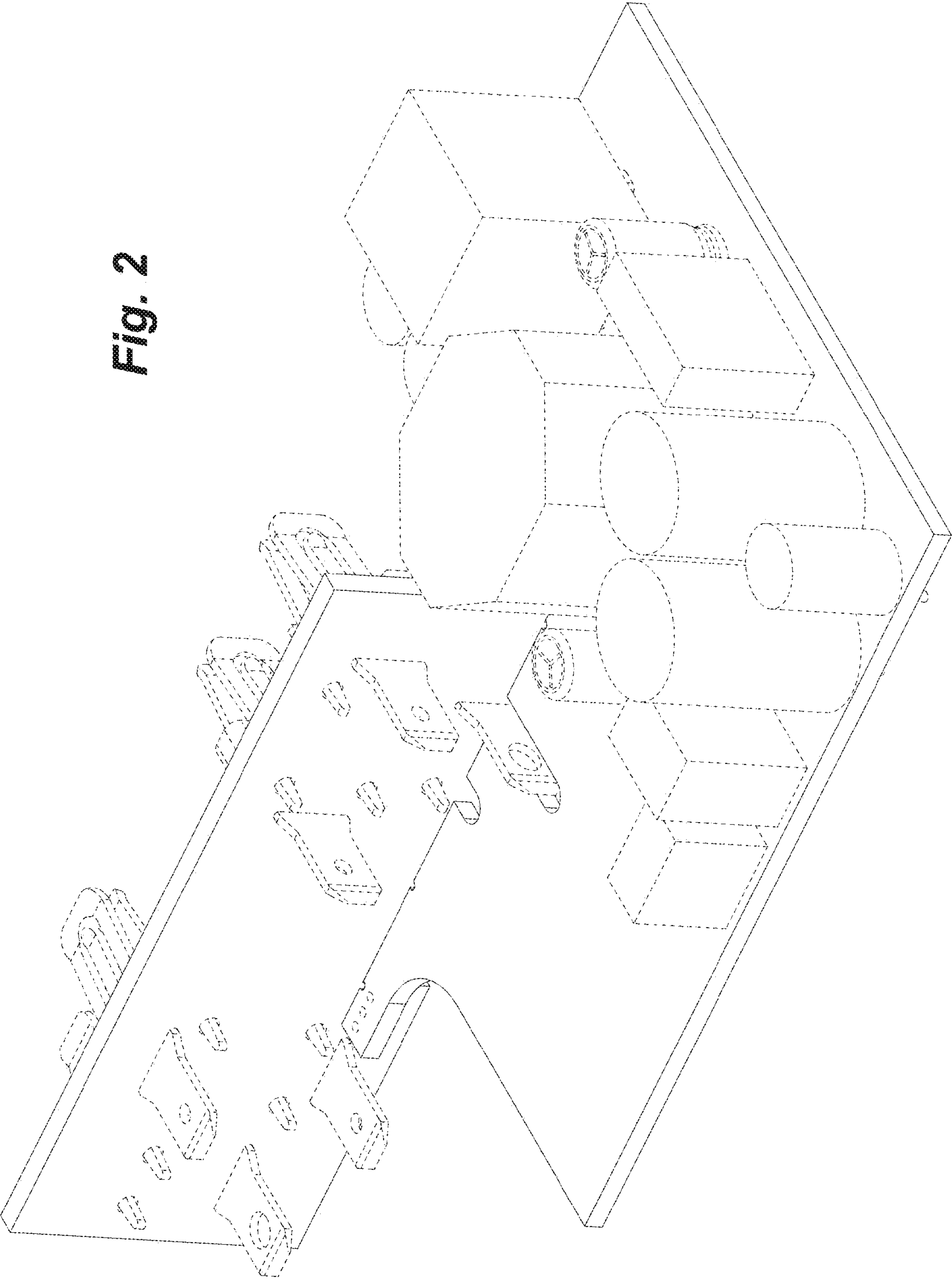
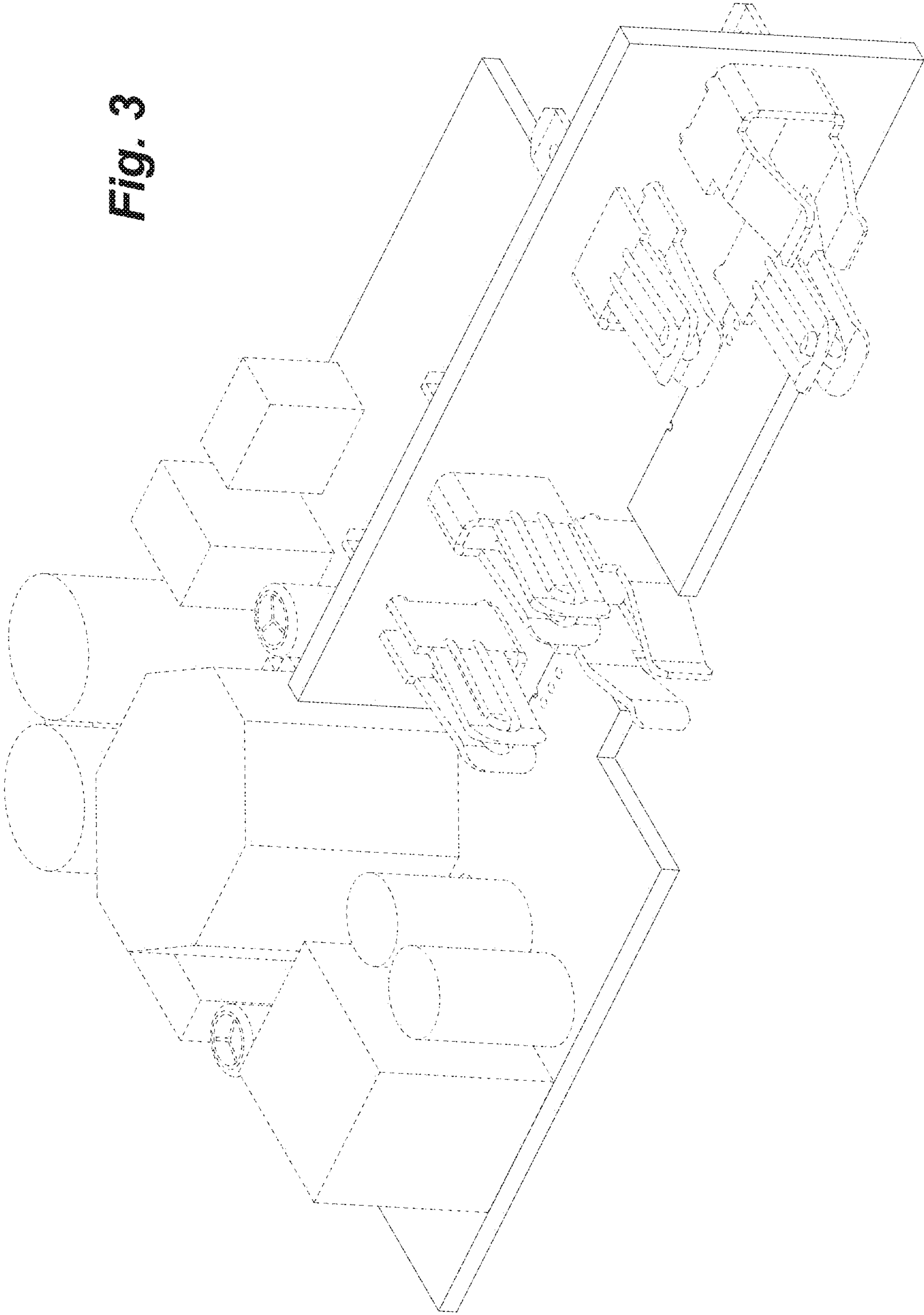


Fig. 3



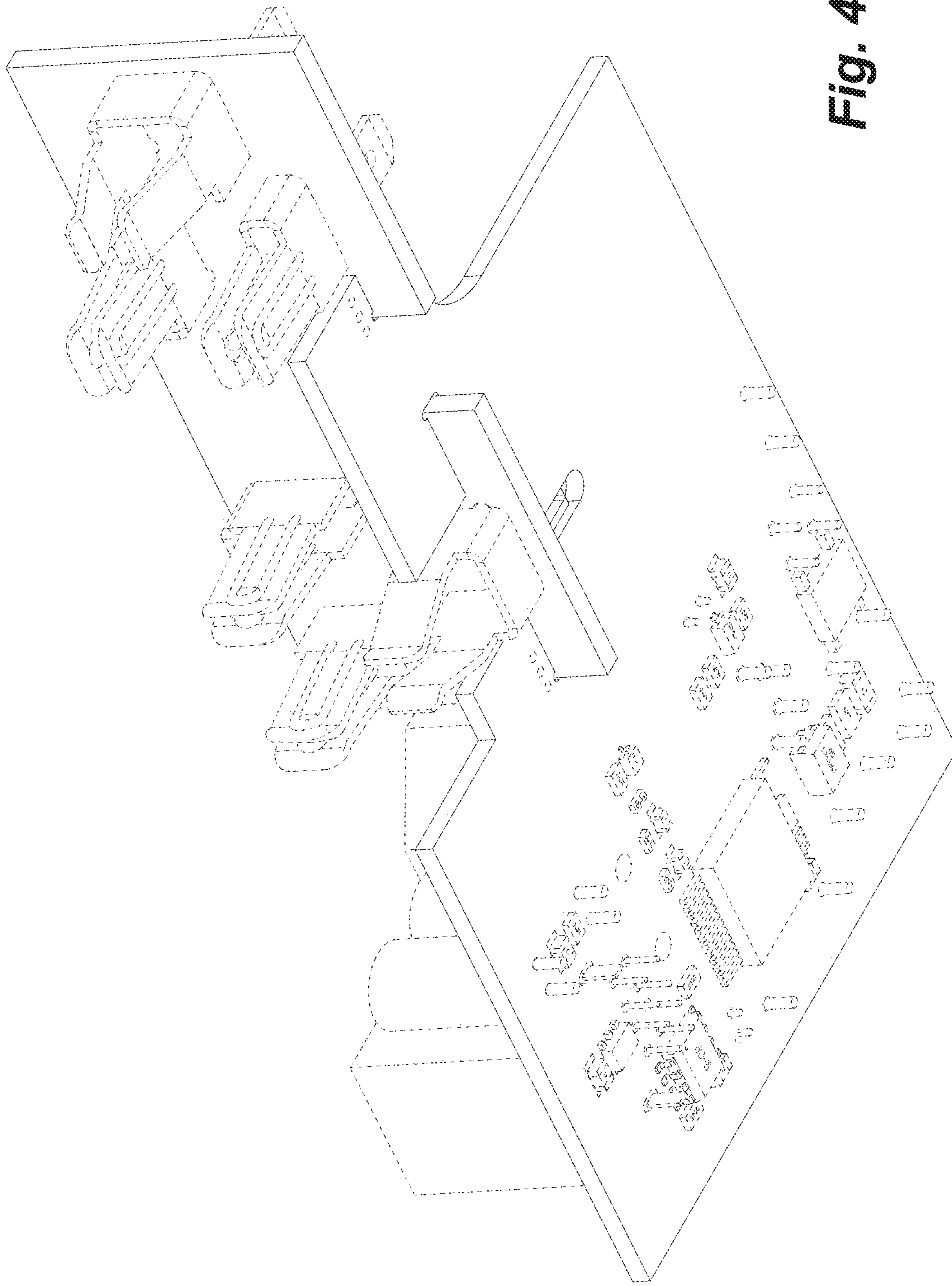


Fig. 4

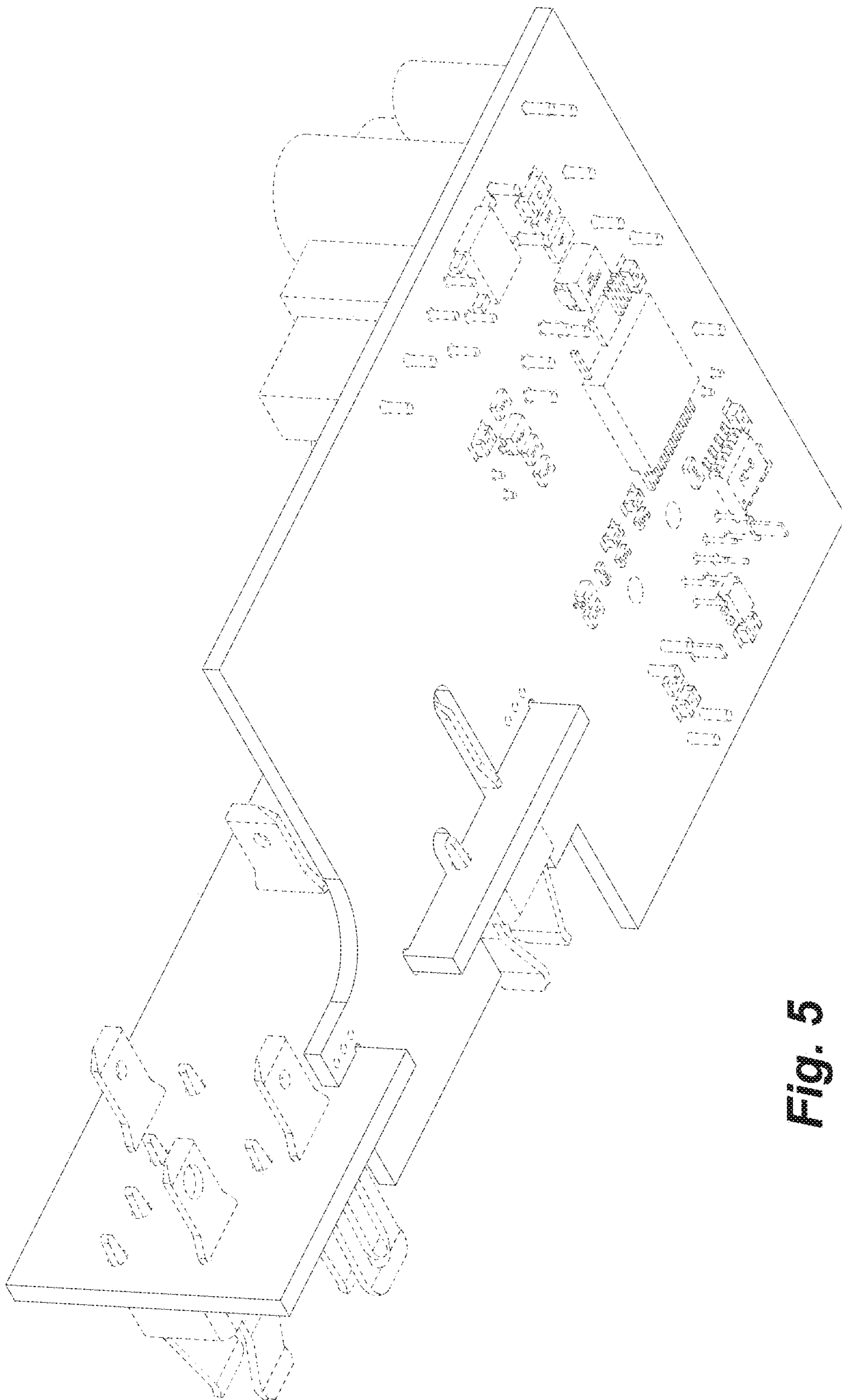
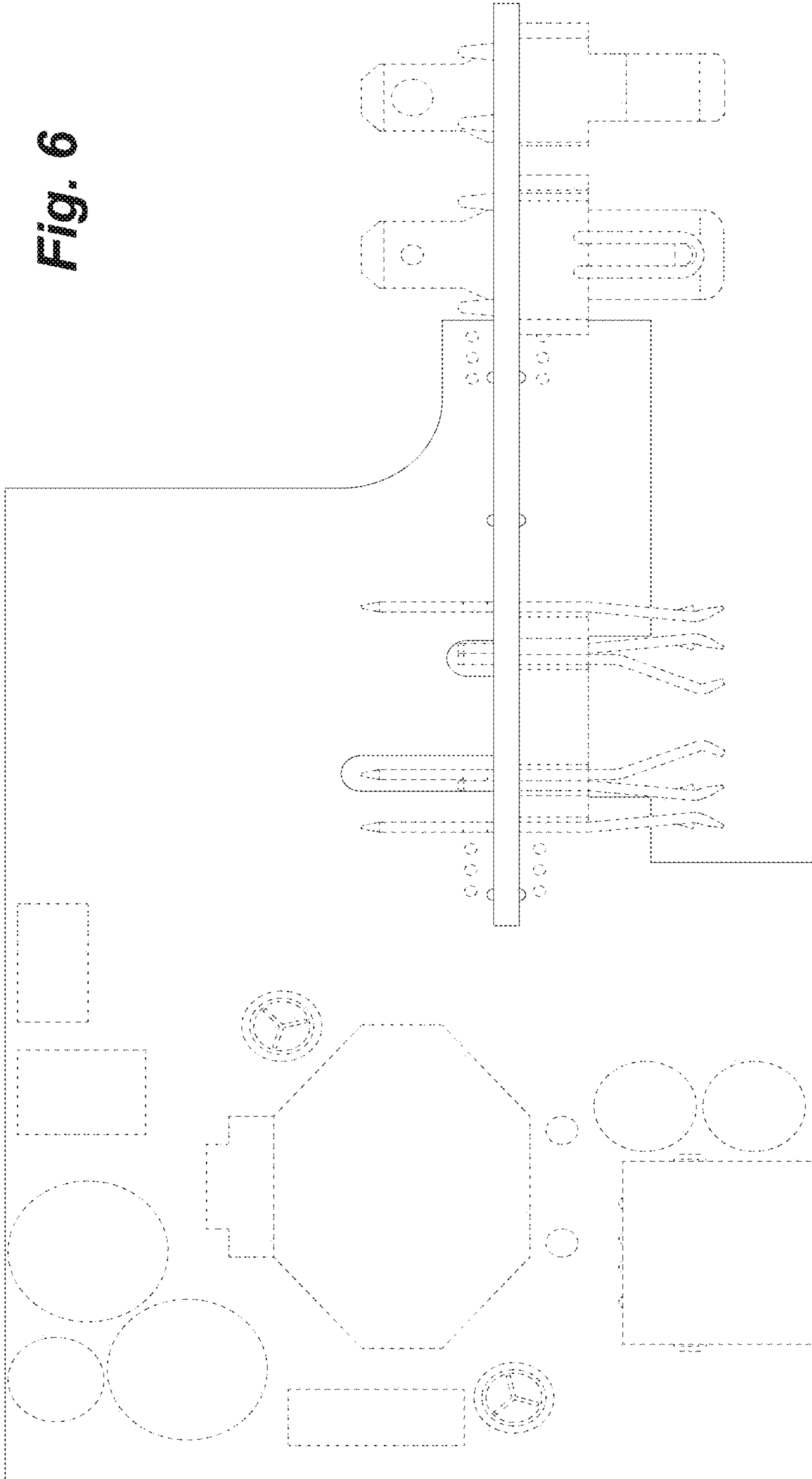


Fig. 5

Fig. 6





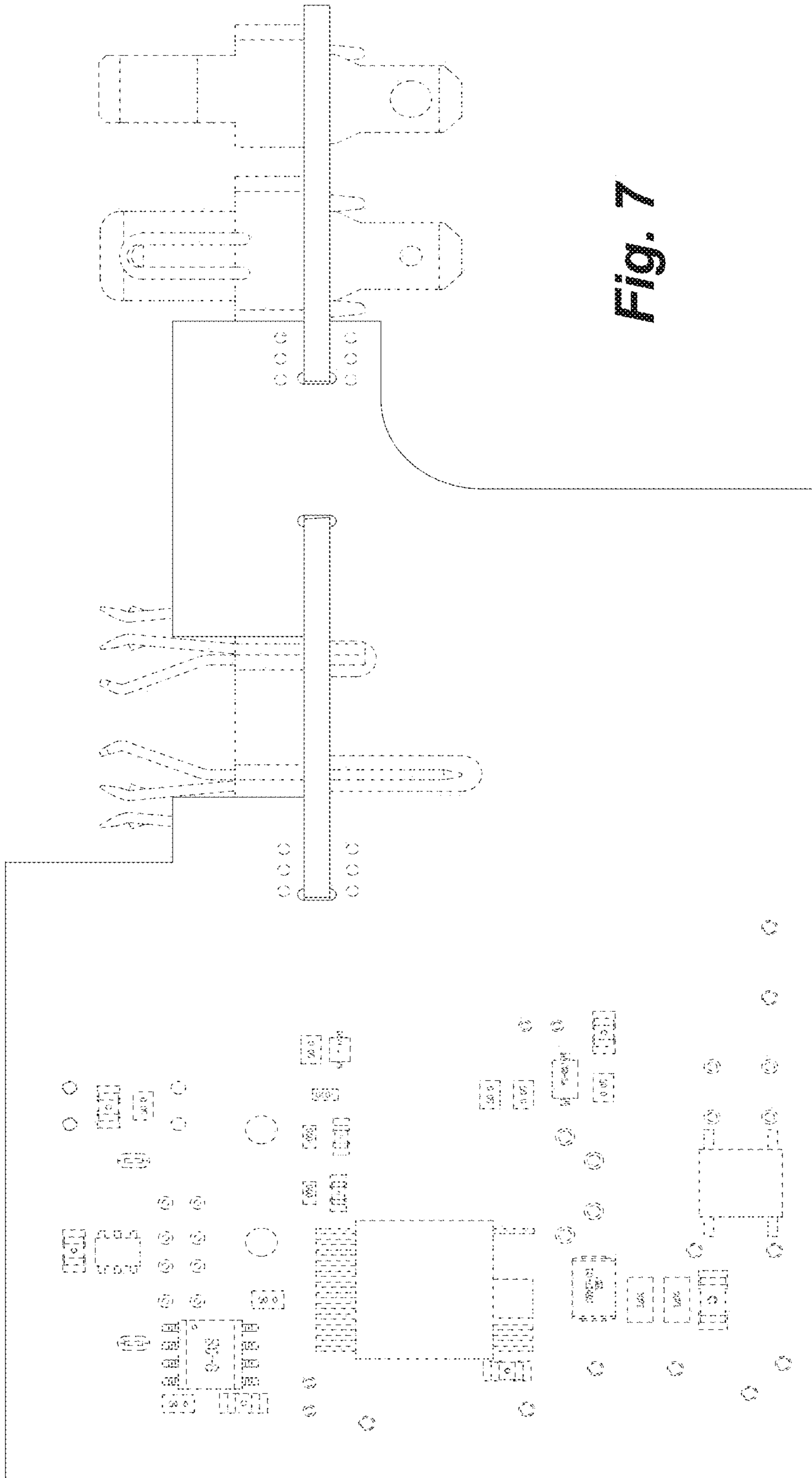


Fig. 7

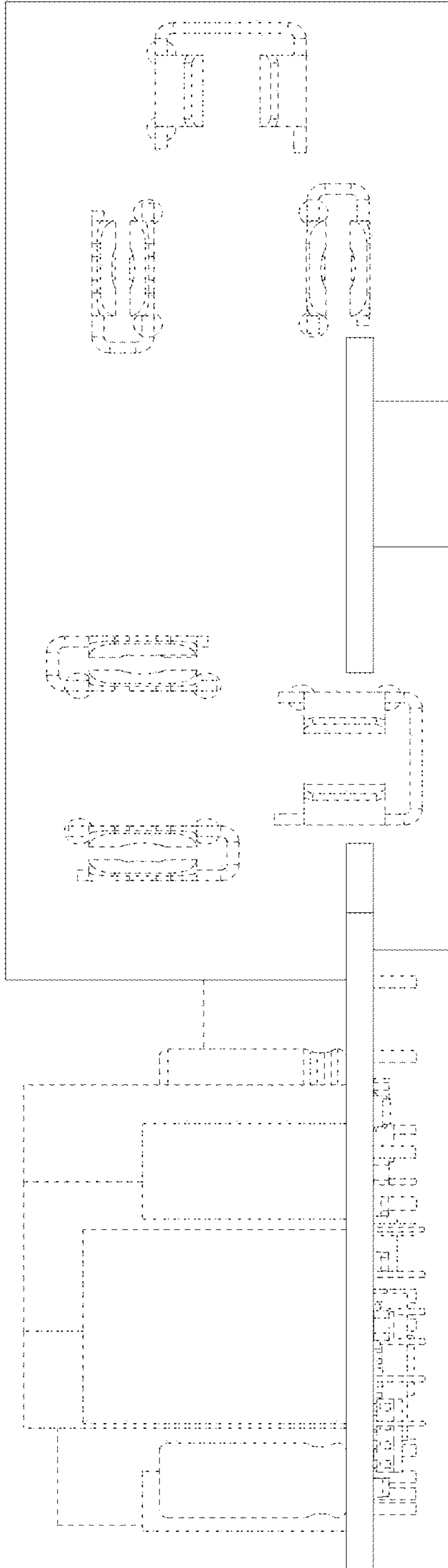


Fig. 8

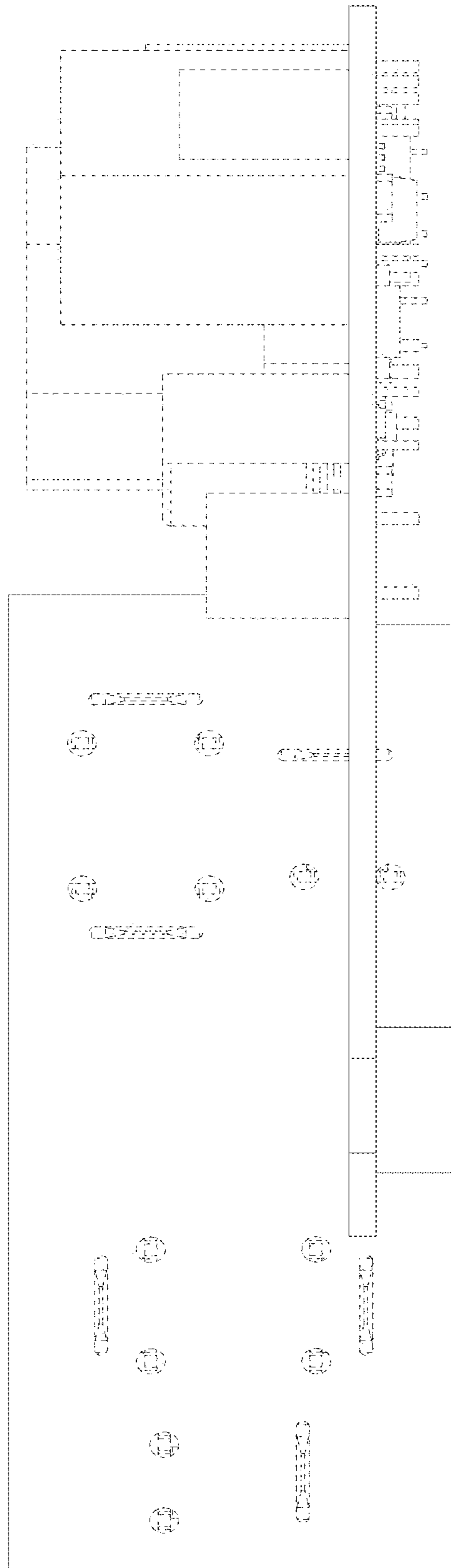
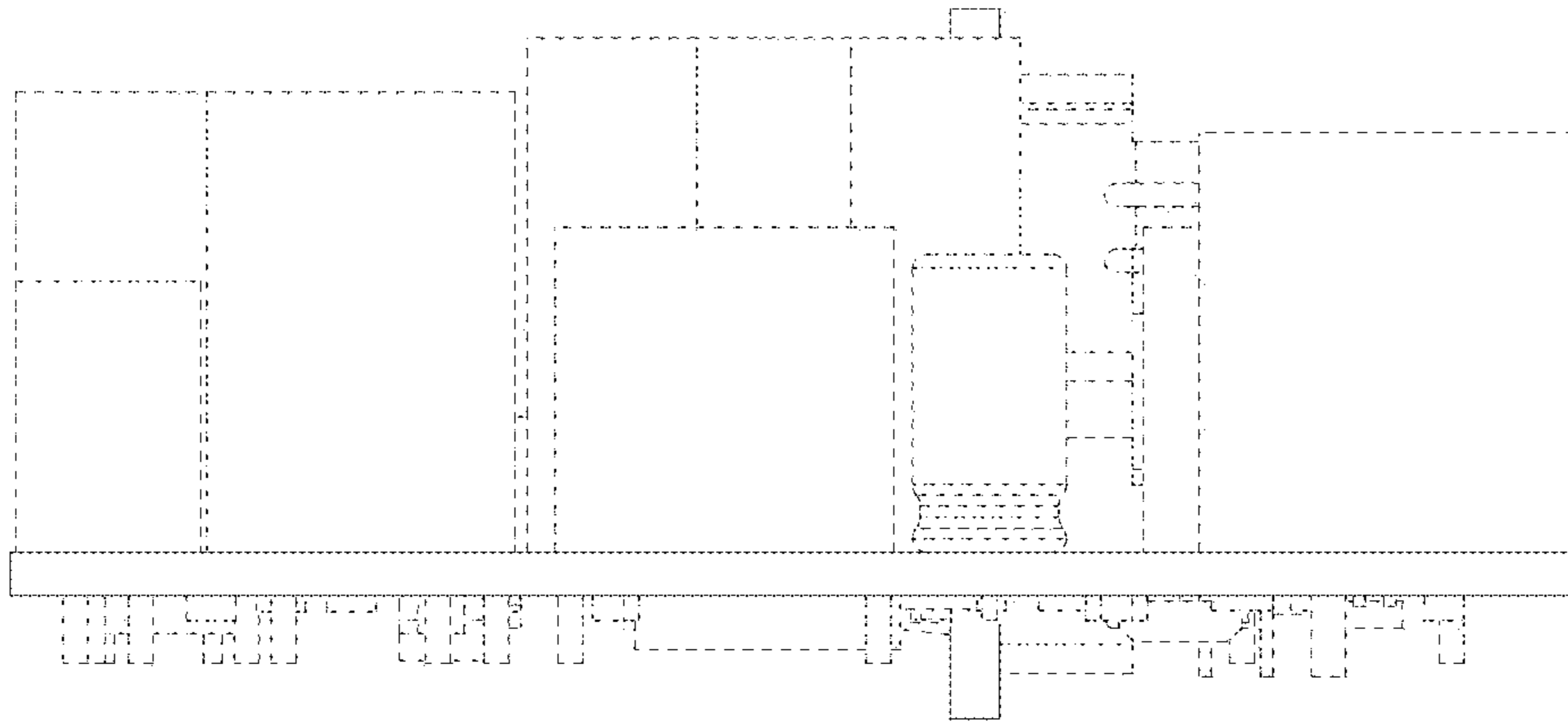
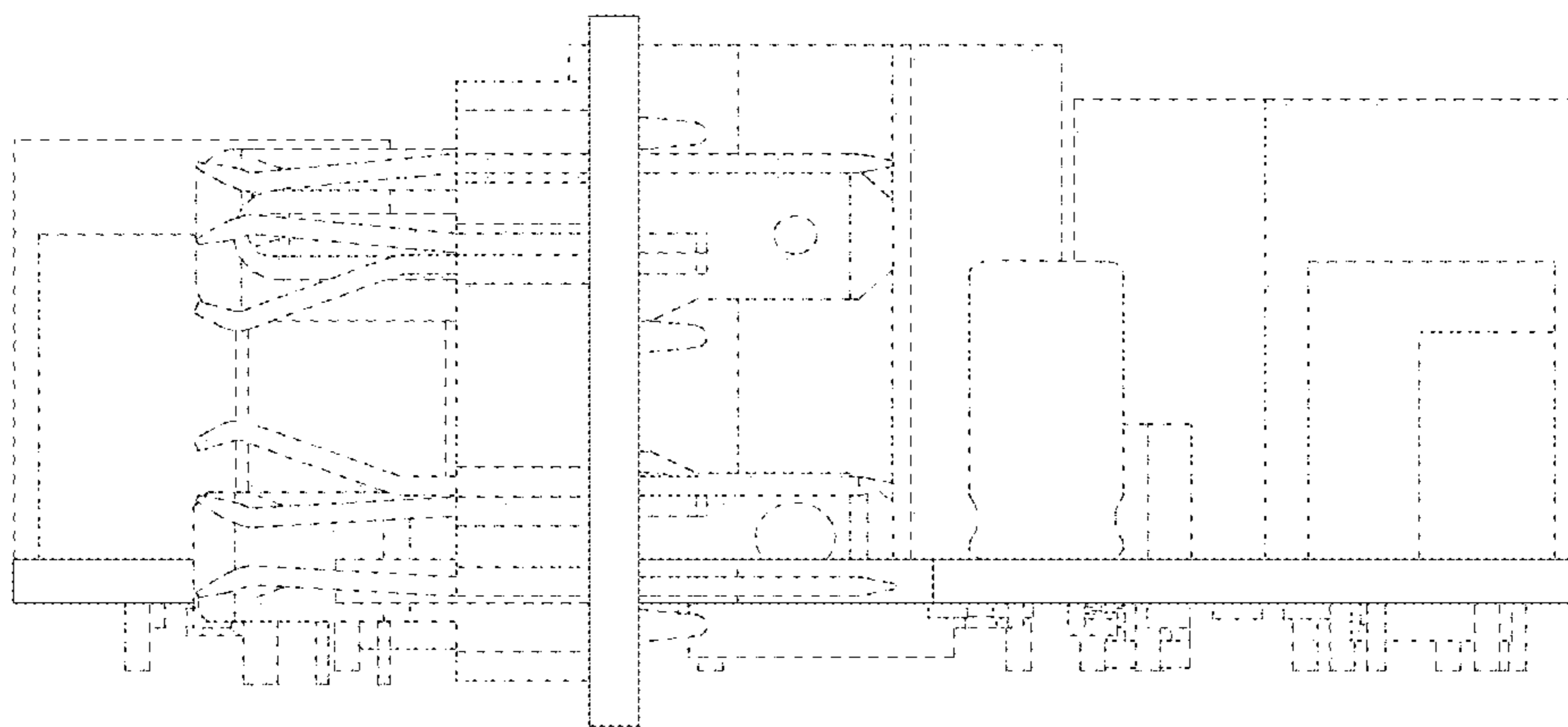


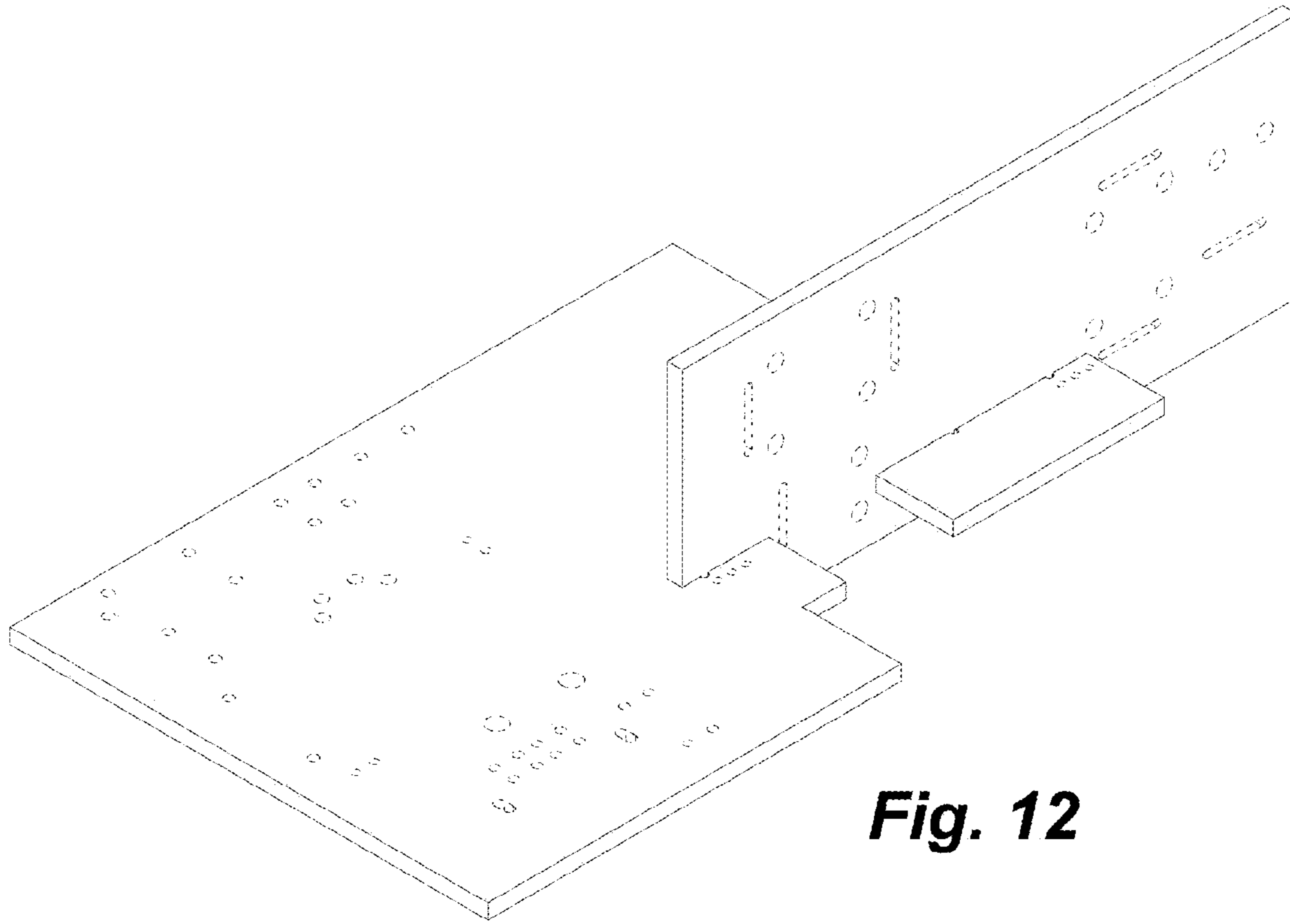
Fig. 9



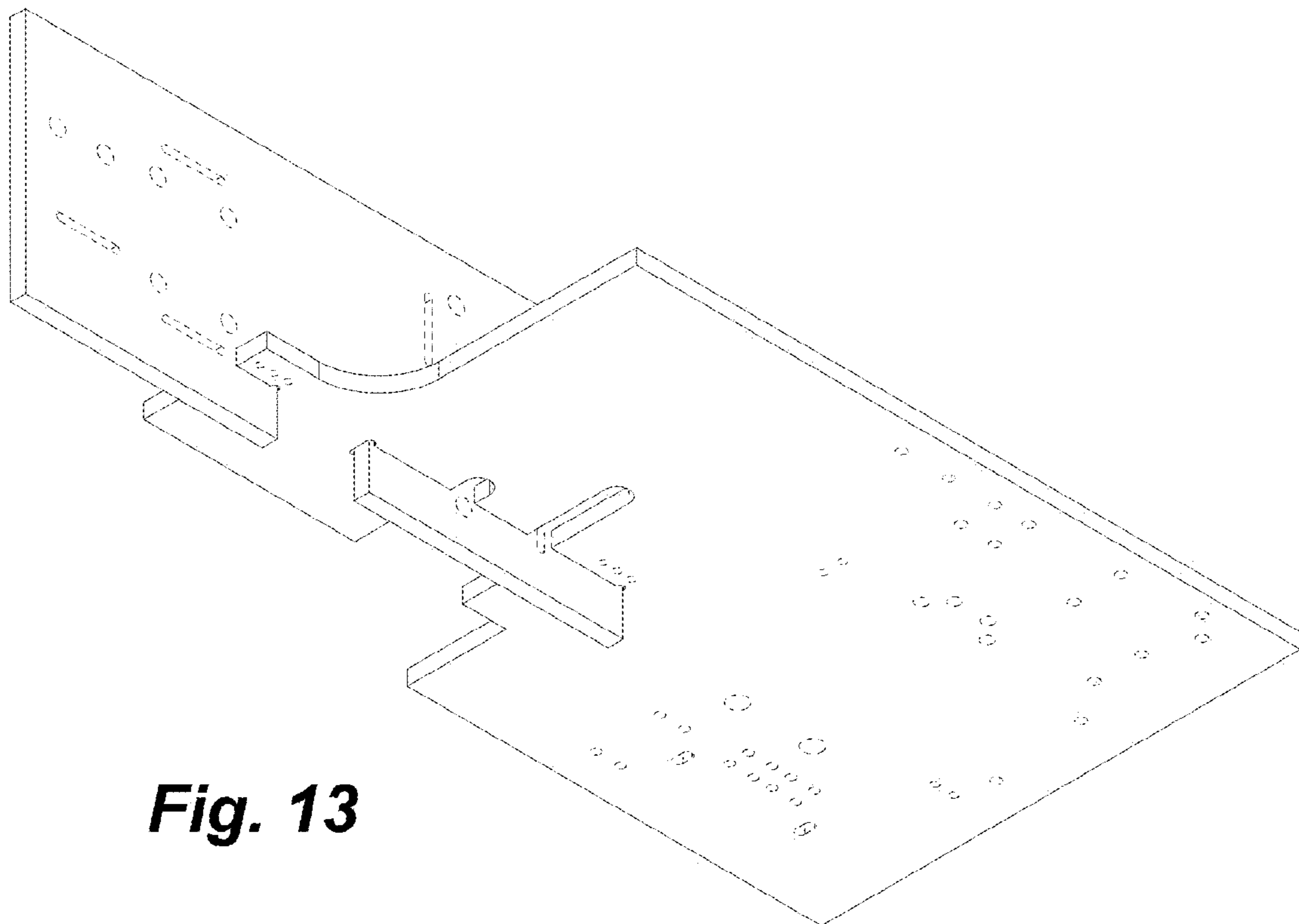
**Fig. 10**



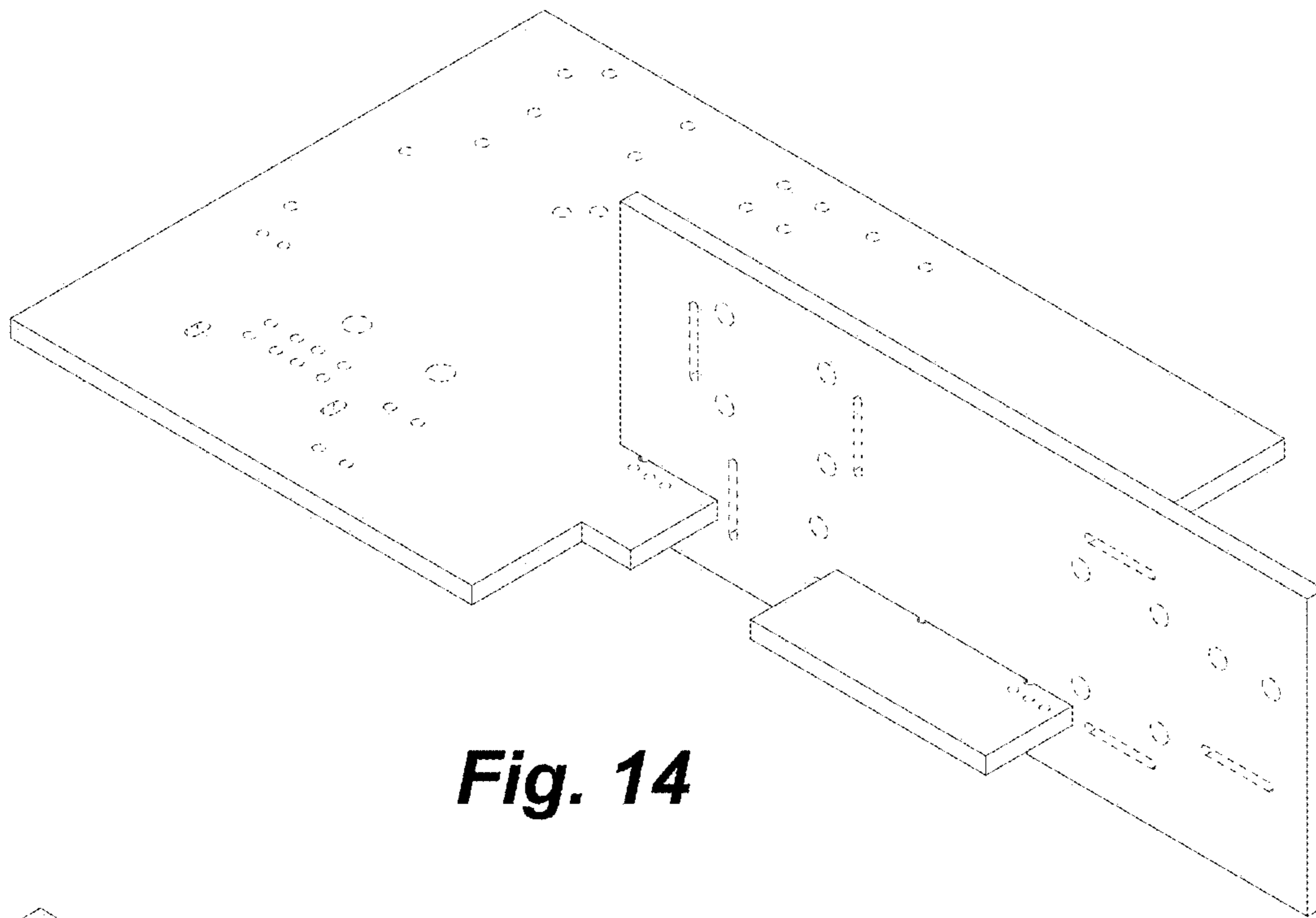
**Fig. 11**



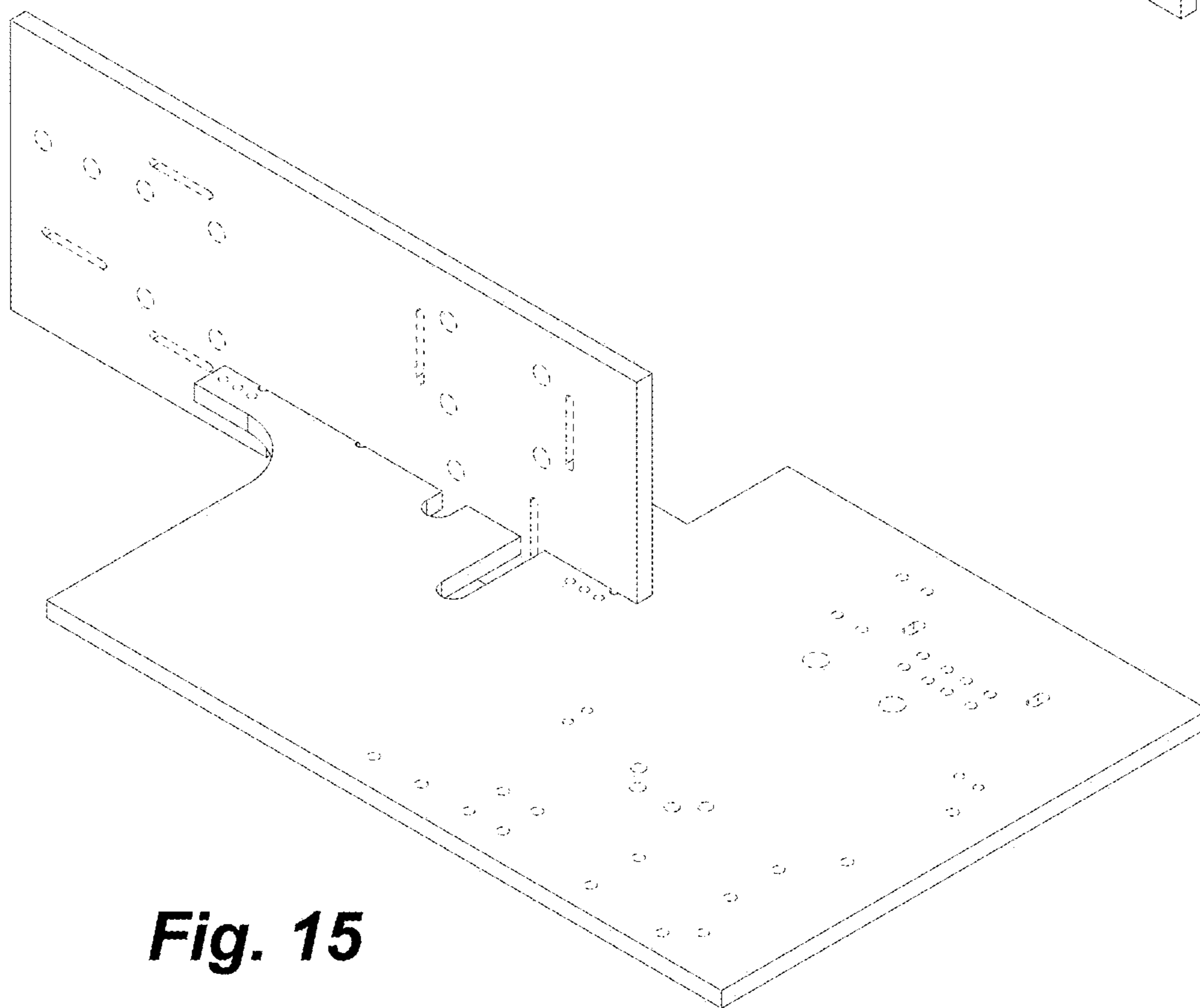
**Fig. 12**



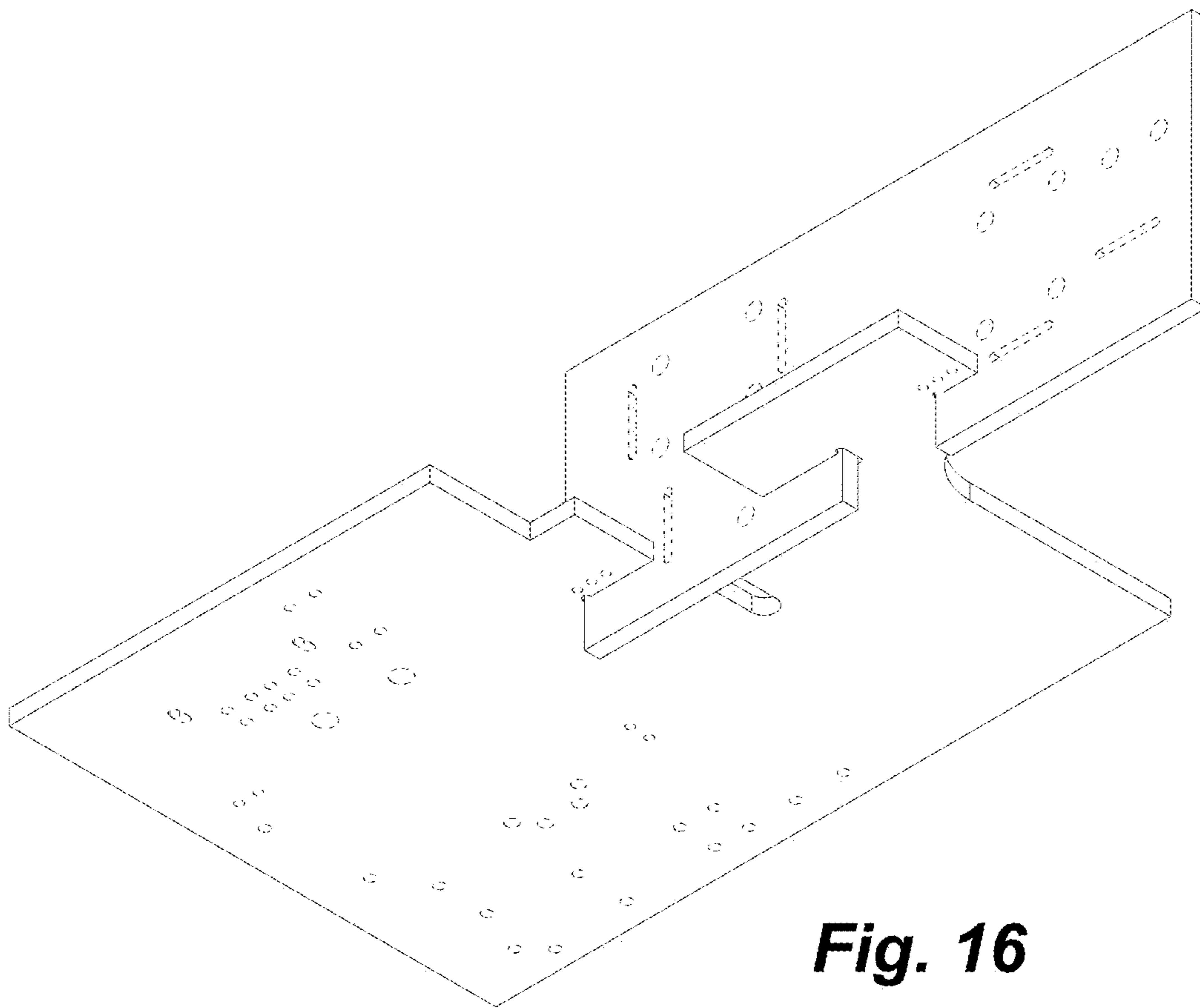
**Fig. 13**



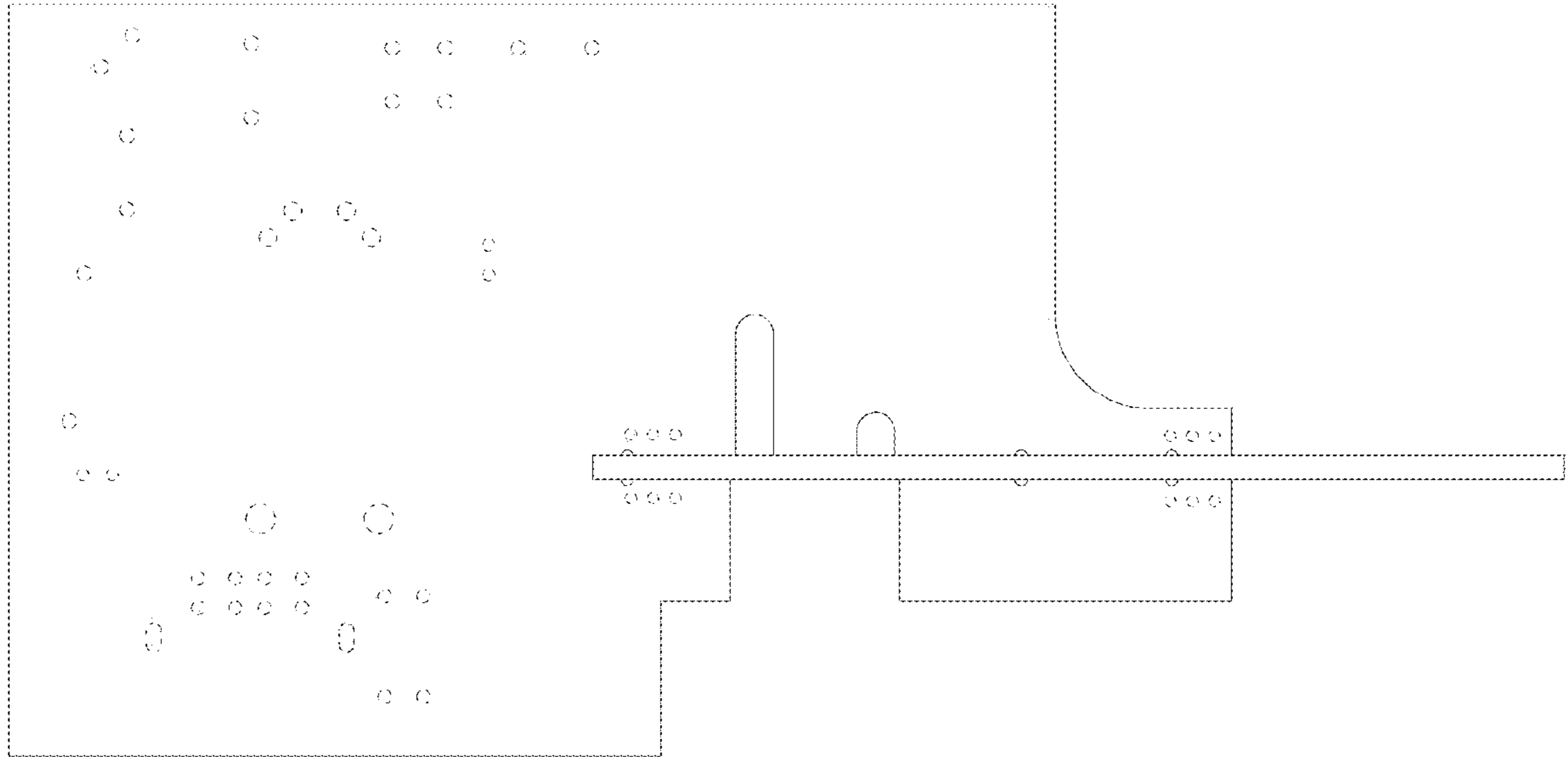
**Fig. 14**



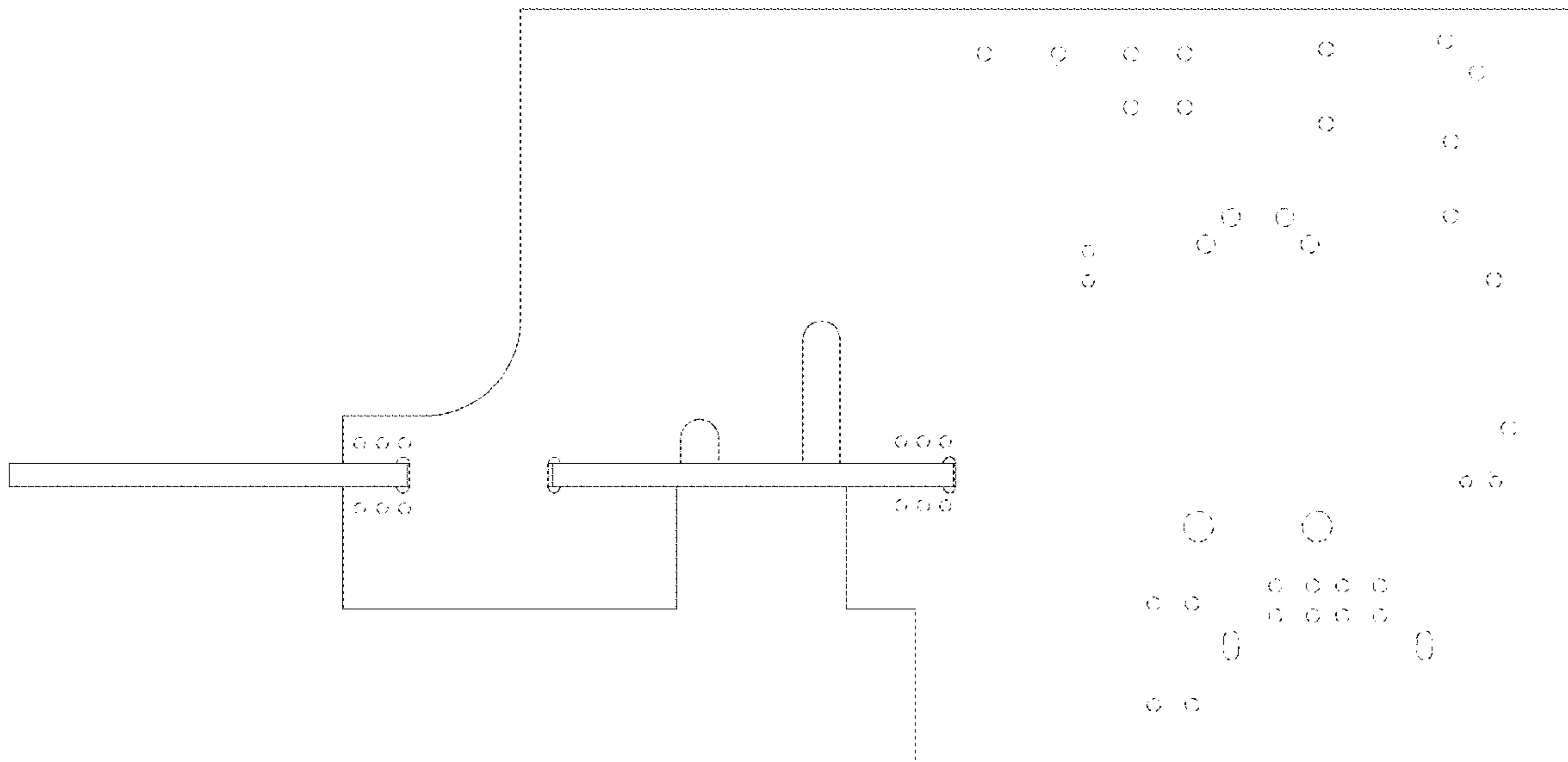
**Fig. 15**



**Fig. 16**

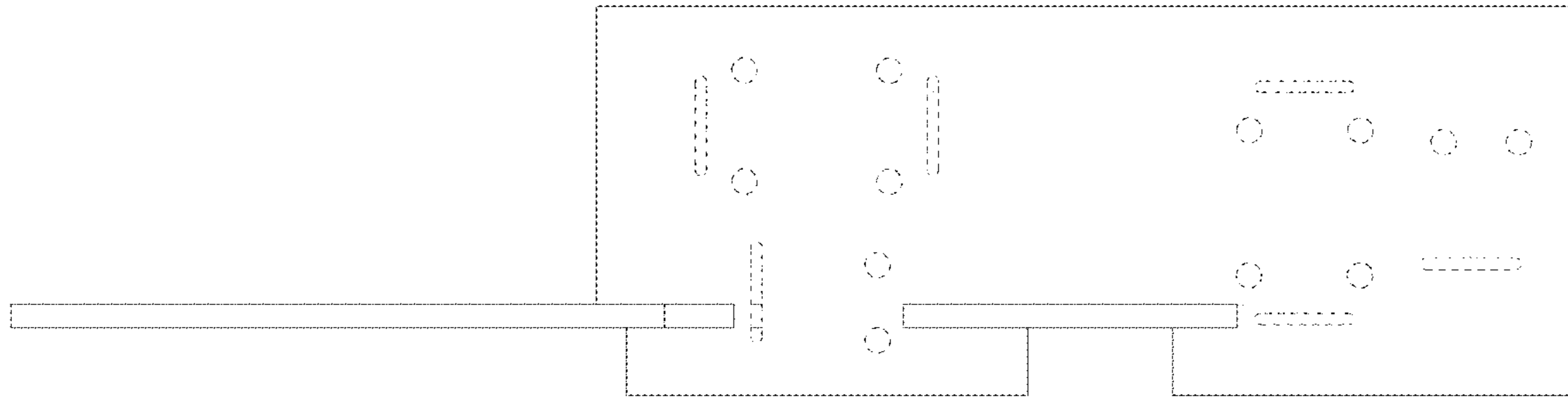


**Fig. 17**

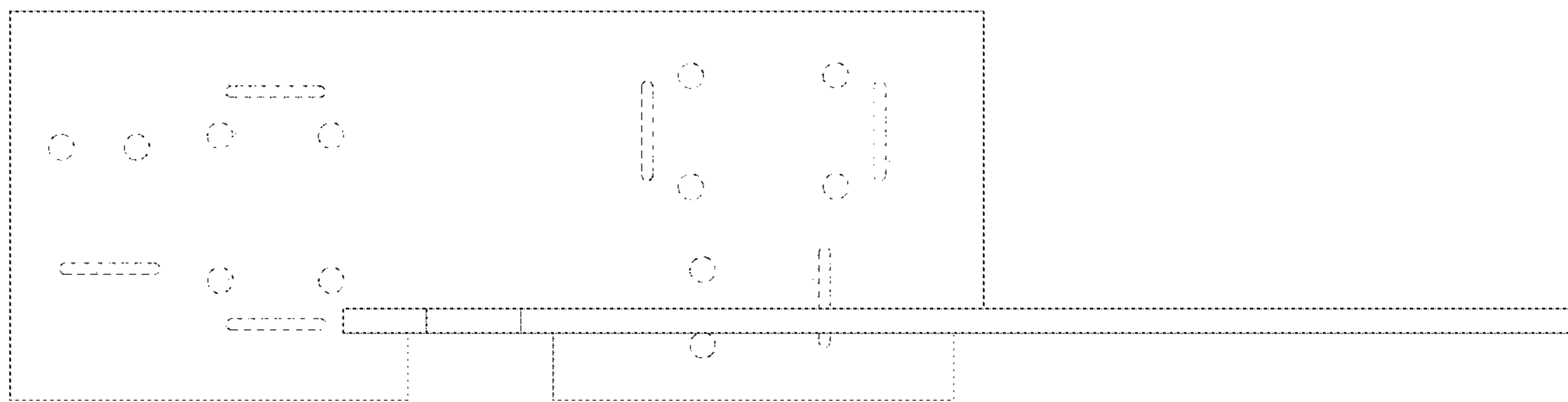


**Fig. 18**





**Fig. 19**



**Fig. 20**